



Final Product/Process Change Notification

Document #:FPCN23658ZN

Issue Date:25 Jan 2022

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| Title of Change: | Wafer fab transfer to onsemi Gresham, Oregon USA from onsemi Fab2, Oudenaarde, Belgium related to Fab2 sale |
| Proposed Changed Material First Ship Date: | 01 Aug 2022 or earlier if approved by customer |
| Current Material Last Order Date: | 28 Feb 2022 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i> |
| Current Material Last Delivery Date: | 31 Jul 2022 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i> |
| Product Category: | Active components – Integrated circuits |
| Contact information: | Contact your local onsemi Sales Office or Bill.Fontes@onsemi.com |
| PCN Samples Contact: | Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. |
| Sample Availability Date: | 01 Feb 2022 |
| PPAP Availability Date: | 15 Mar 2022 |
| Additional Reliability Data: | Contact your local onsemi Sales Office or Catherine.DeKeukeleire@onsemi.com |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com . |
| Change Category | |
| Category | Type of Change |
| Process - Wafer Production | Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter |
| Equipment | Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process. |
| Process - Assembly | Change of leadframe base material, Change of product marking |
| Description and Purpose: | |
| After the announcement on February 03rd, 2020 of the sale of Fab2, onsemi pursues the transfer of relevant products. Before Last Order Date above: customers must provide Last-Time-Buy volume for products that will be transferred to manufacture the bridge-build quantity in the current facility (fab2) before the selling. After the last order date above: the orders will be placed on the new part number (replacement part) or on the receiving fab (products with the same part number). Last Delivery Date above: subject to a commercial agreement, onsemi may extend the deliveries outside the 06 months windows which is the proposed date of implementation in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements but after depletion of inventory of the current material. However, such extended delivery conditions could be subject to an extension of the date code currently at 12 months | |



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| | Before Change Description | After Change Description |
|-----------------|-----------------------------|--|
| Wafer Fab Site | onsemi, Oudenaarde, Belgium | onsemi, Gresham, Oregon, USA |
| Wafer Size | 150 mm | 200 mm |
| Package Marking | NCV7751 | NCV7751-G |
| Equipment | 150 mm Production Line | 200 mm Production Line |
| Leadframe | Standard SSOP | SSOP with Roughening to Improve Delamination Performance |

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| Reason / Motivation for Change: | Source/Supply/Capacity Changes |
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability: | <p>The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p> |

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| Sites Affected: | |
| onsemi Sites | External Foundry/Subcon Sites |
| onsemi Carmona, Philippines | None |
| onsemi Oudenaarde, Belgium | |
| onsemi, Gresham United States | |

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| Marking of Parts/ Traceability of Change: | Package marking will be updated. |
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| Reliability Data Summary: NOTE: AEC-1pager is attached. <i>To view attachments:</i> <i>1. Download pdf copy of the PCN to your computer</i> <i>2. Open the downloaded pdf copy of the PCN</i> <i>3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field</i> <i>4. Then click on the attached file</i> |
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| Electrical Characteristics Summary: Electrical characteristics are not impacted. |
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| List of Affected Parts: Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u> . |
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| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|-----------------------|
| NCV7751DQR2G | NA | NCV7751DQR2G |